



Role of Materials for Semiconductor Manufacturing Enabling Future Nano-optical Applications and Devices

Thomas Gädda, CTO

Who we are

We are an innovative materials company with strong R&D capabilities and a portfolio of unique patents. We are one of the only European suppliers of EUV lithography materials. PiBond's materials have been adopted in the latest semiconductor devices globally.

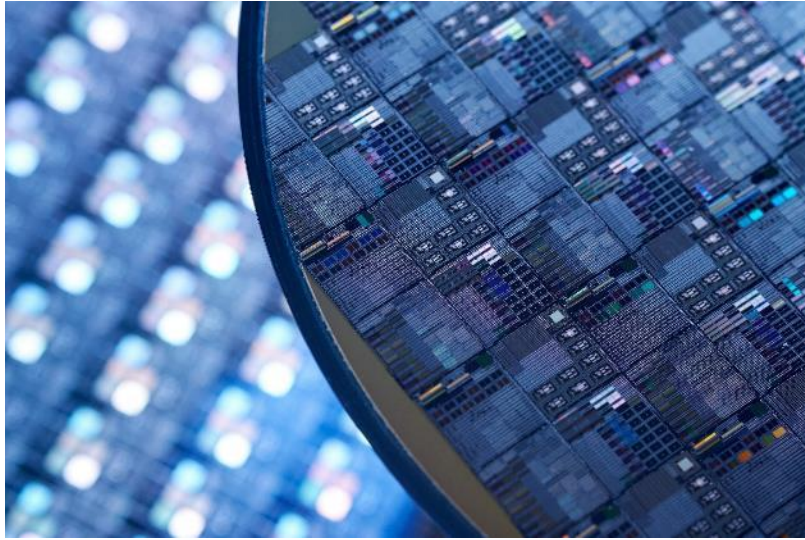
Our Experienced global management team includes industry veterans from some of the largest Semiconductor chip and device companies.

We have an audited supplier track record to the semiconductor industry from our 3000 square meter PPT (*parts per trillion*) Clean Room production facility in Finland.

PiBond



PiBond is a leading innovator of Advanced Materials

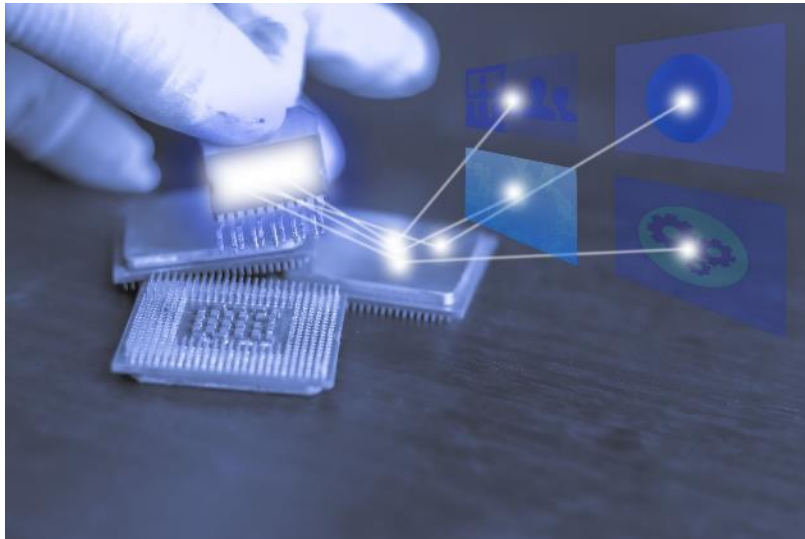


PRESENT

Semiconductor Dielectrics
for State-of-the-Art Applications

Optical Coatings for
Image Sensors

Enabling Layers for
Sub-5nm microelectronics

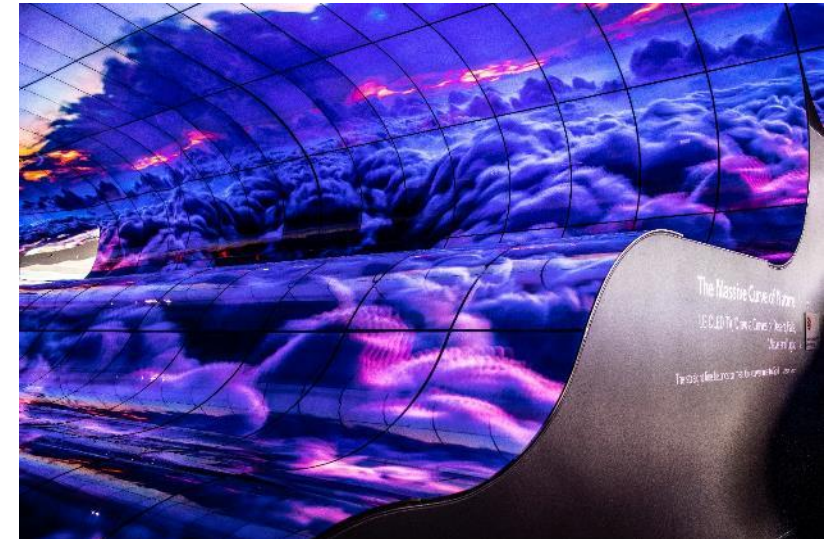


FUTURE

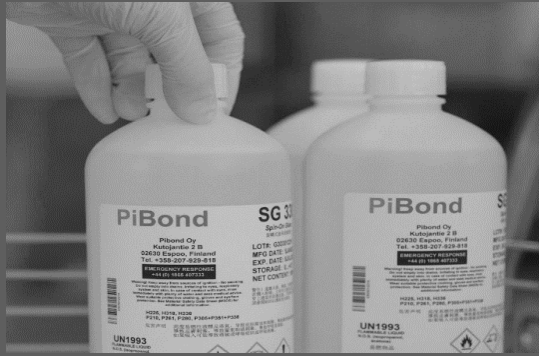
Future Data Transfer
Through Photonics

Semiconductor-level
Precision and Reliability
to Photonic Applications

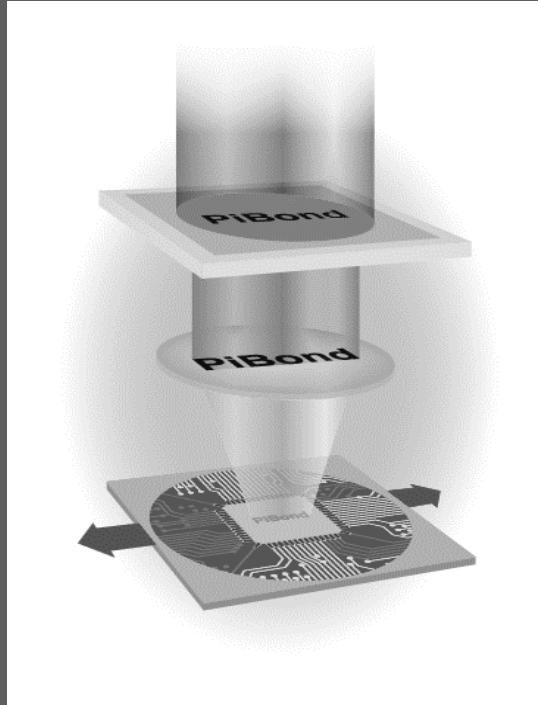
Devices and components
enabled by novel processes



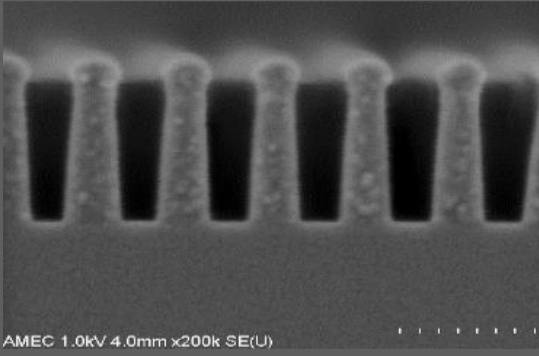
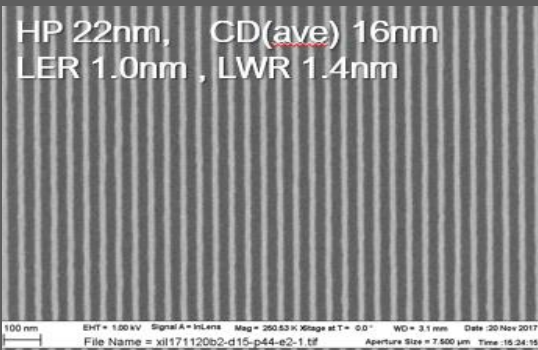
Advanced Lithography



Demand for
Inorganic solutions

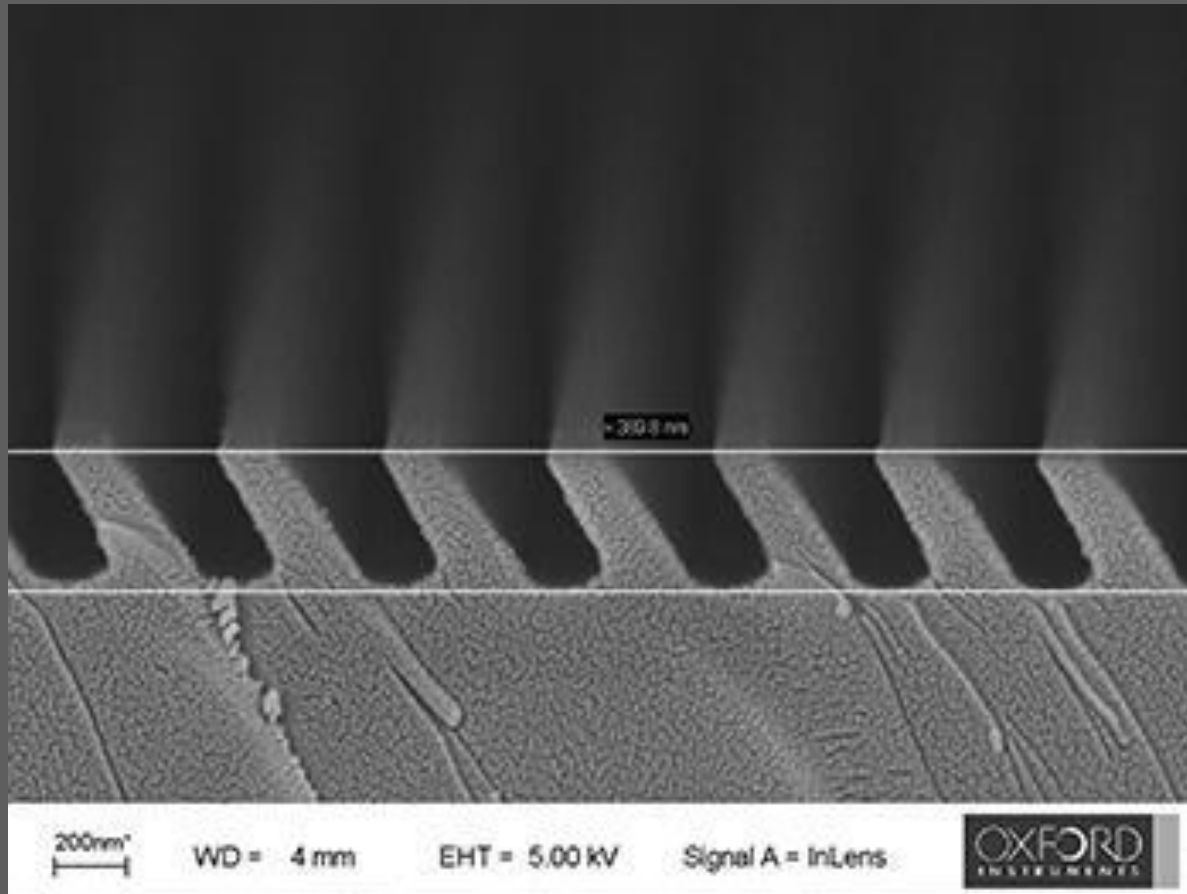


Industry proven
stack <math><5\text{nm}</math>

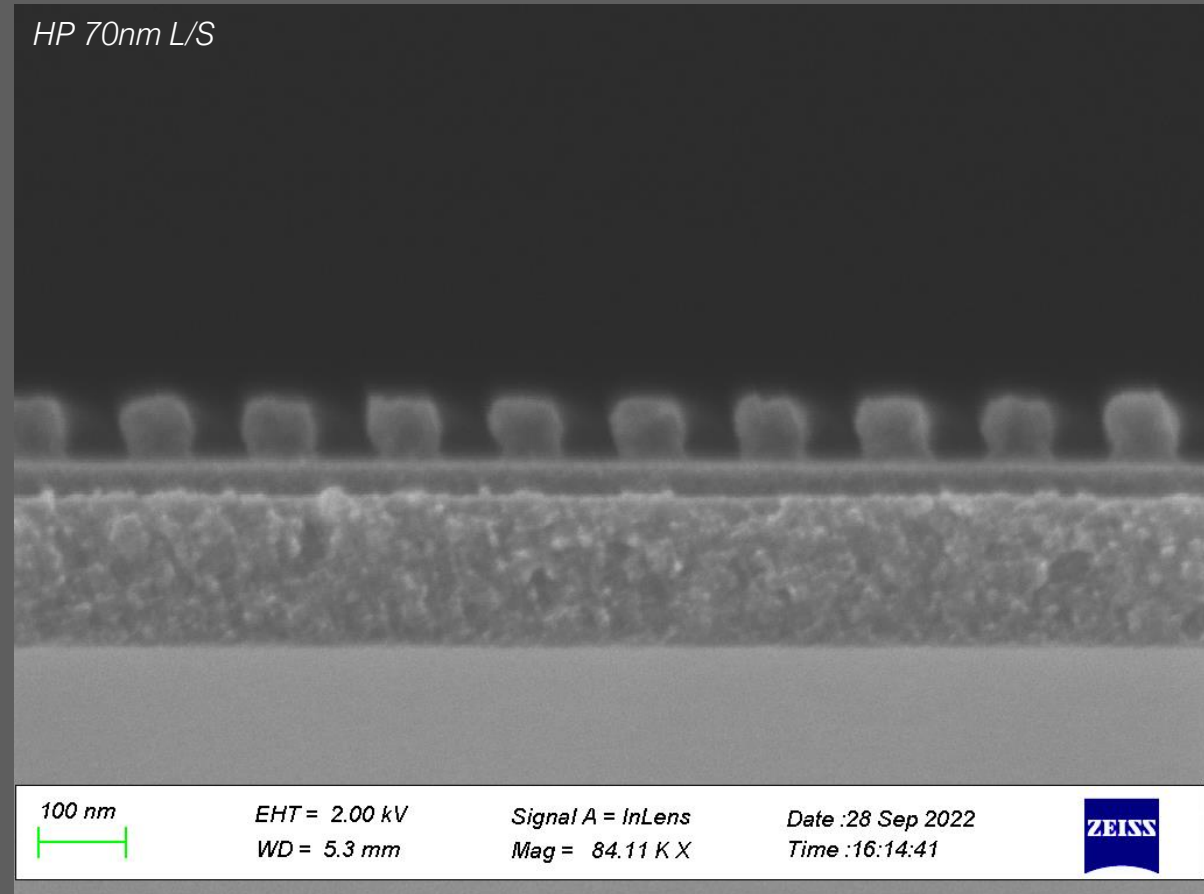


Leading Etch
selectivity for future
devices

Advanced Lithography Materials for line patterning

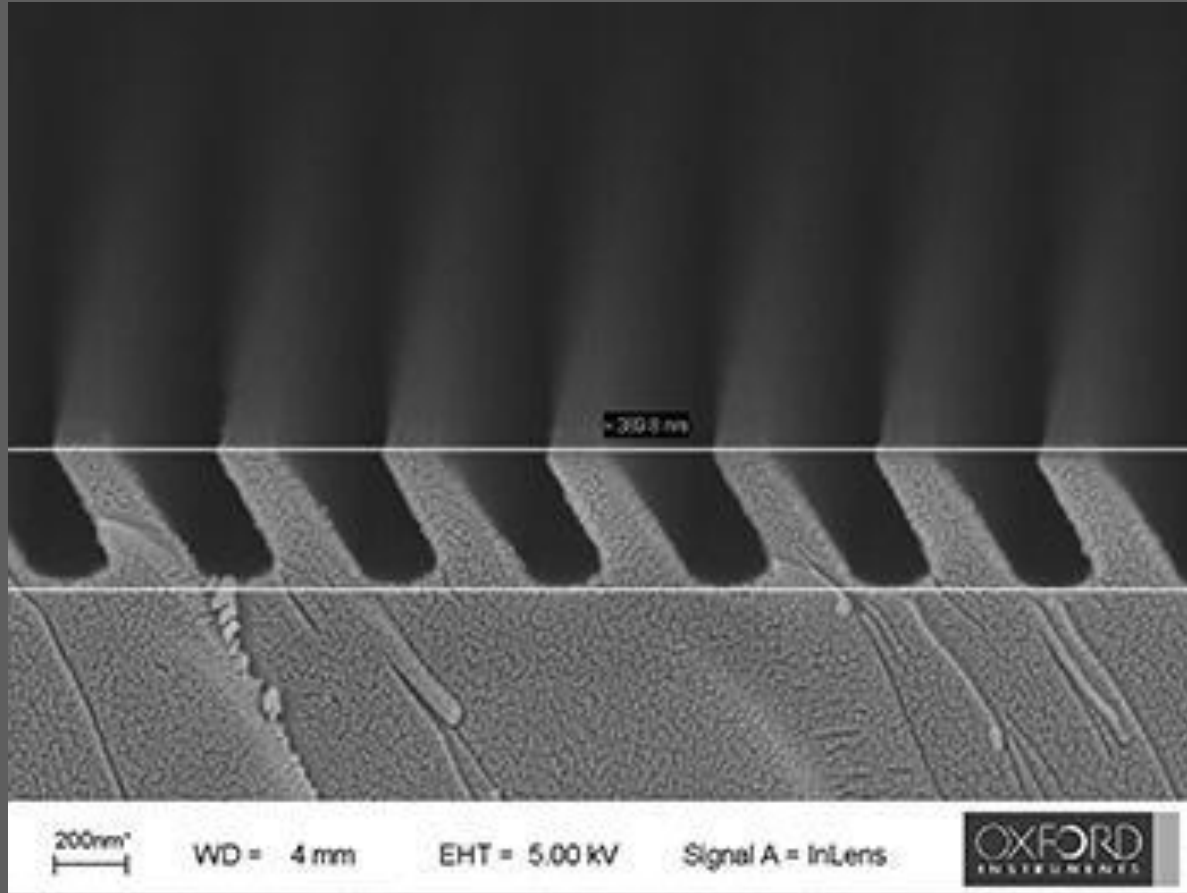


<https://plasma.oxinst.com/blog/2020/3-steps-for-surface-relief-gratings>

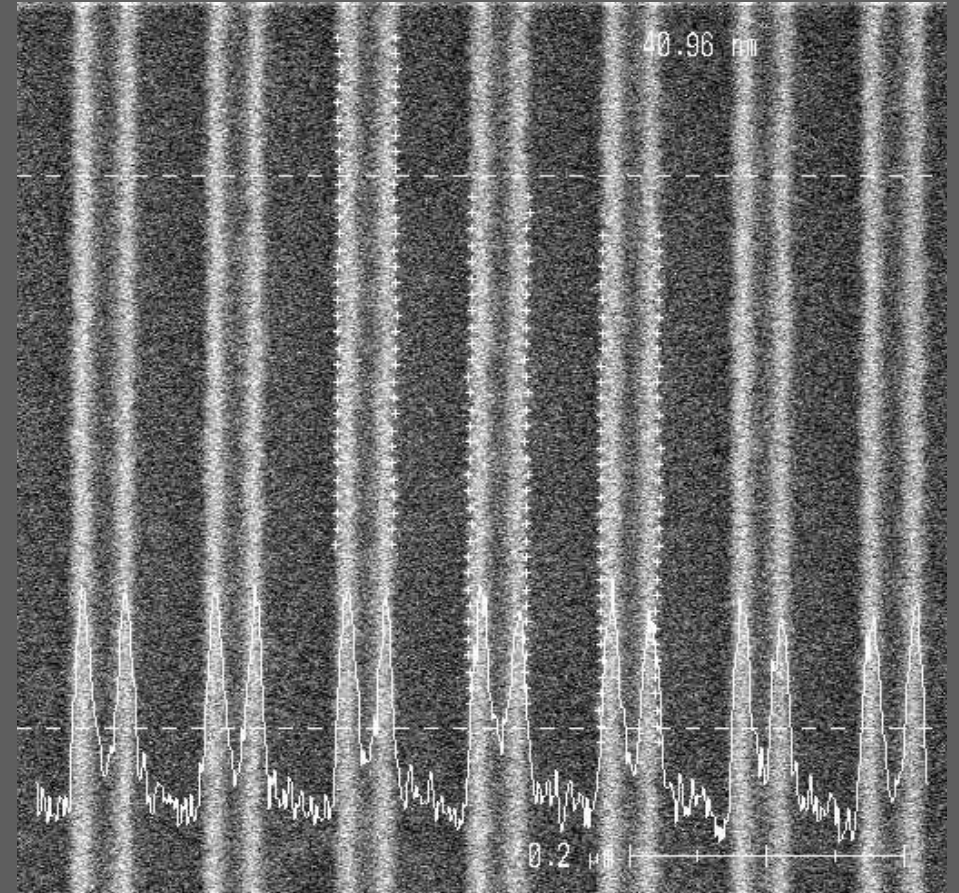


Photolithography etch hard masks

Advanced Lithography Materials for line patterning

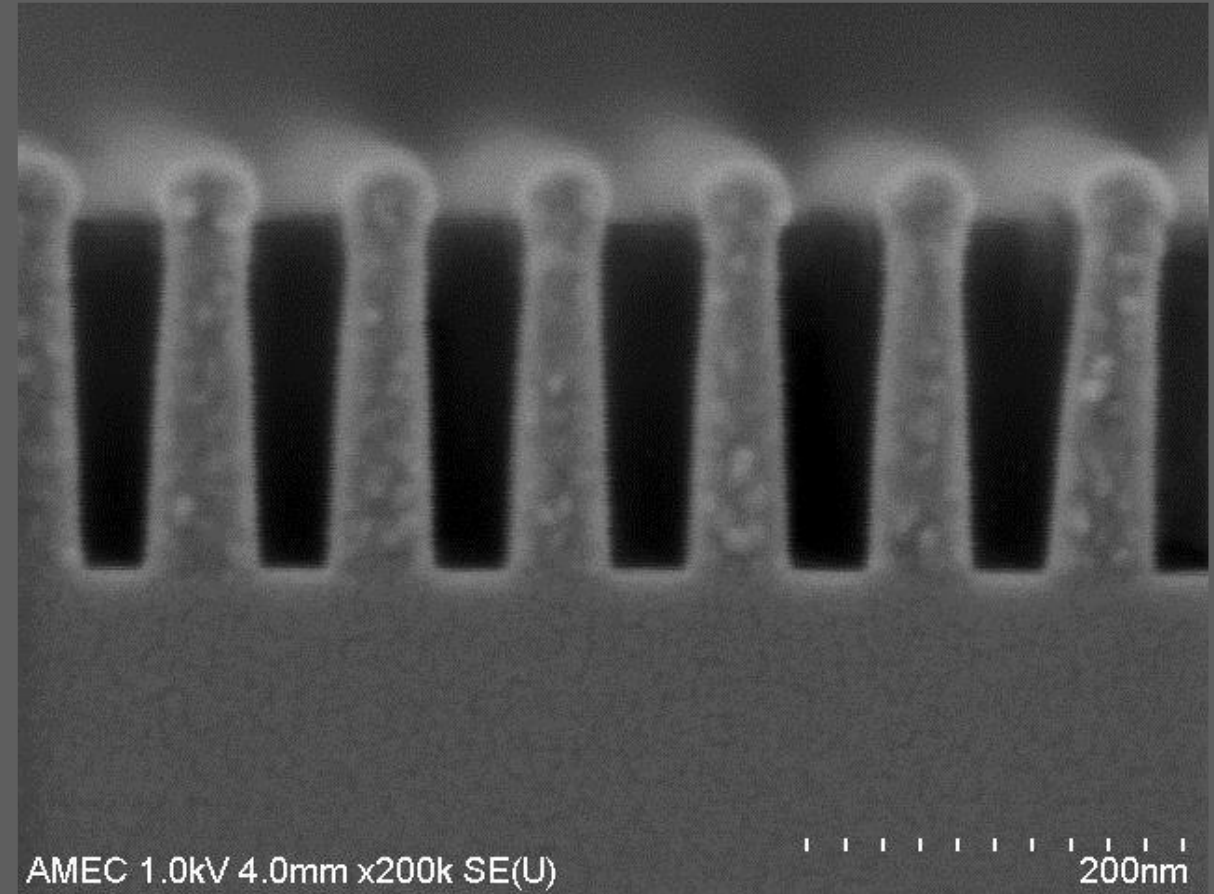
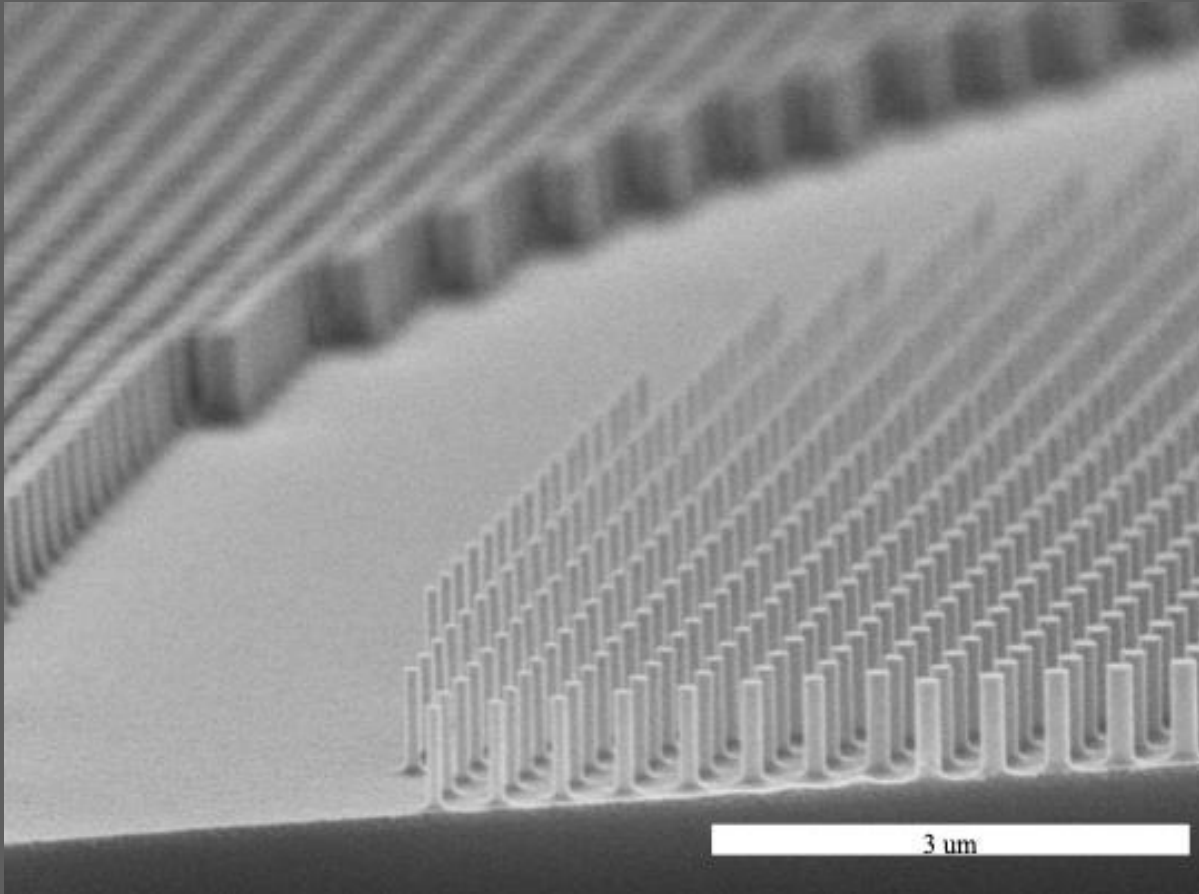


<https://plasma.oxinst.com/blog/2020/3-steps-for-surface-relief-gratings>



Silicon hard mask materials for advanced lithography

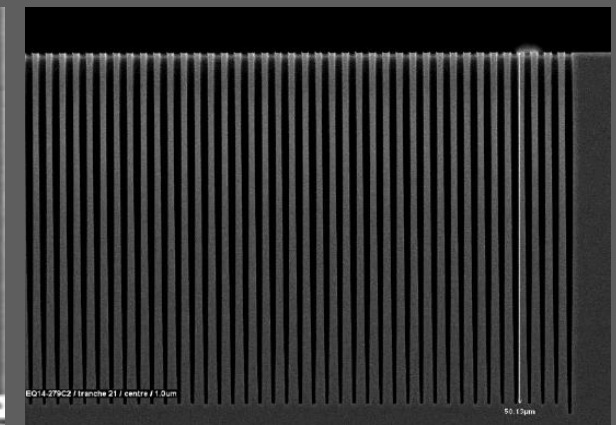
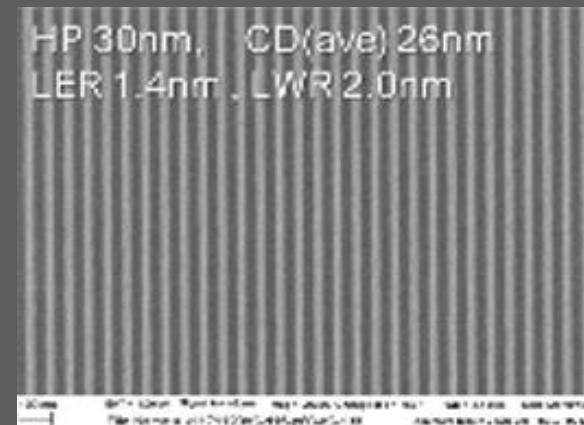
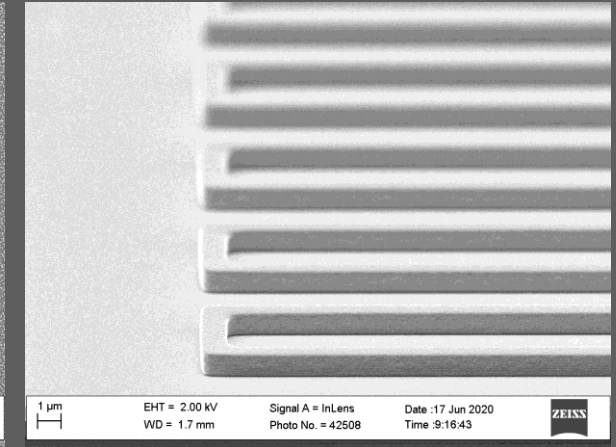
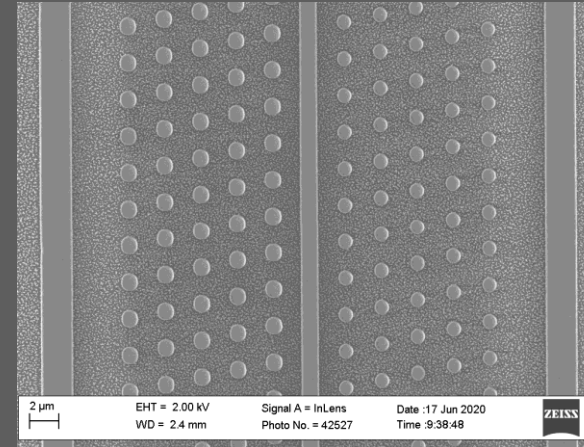
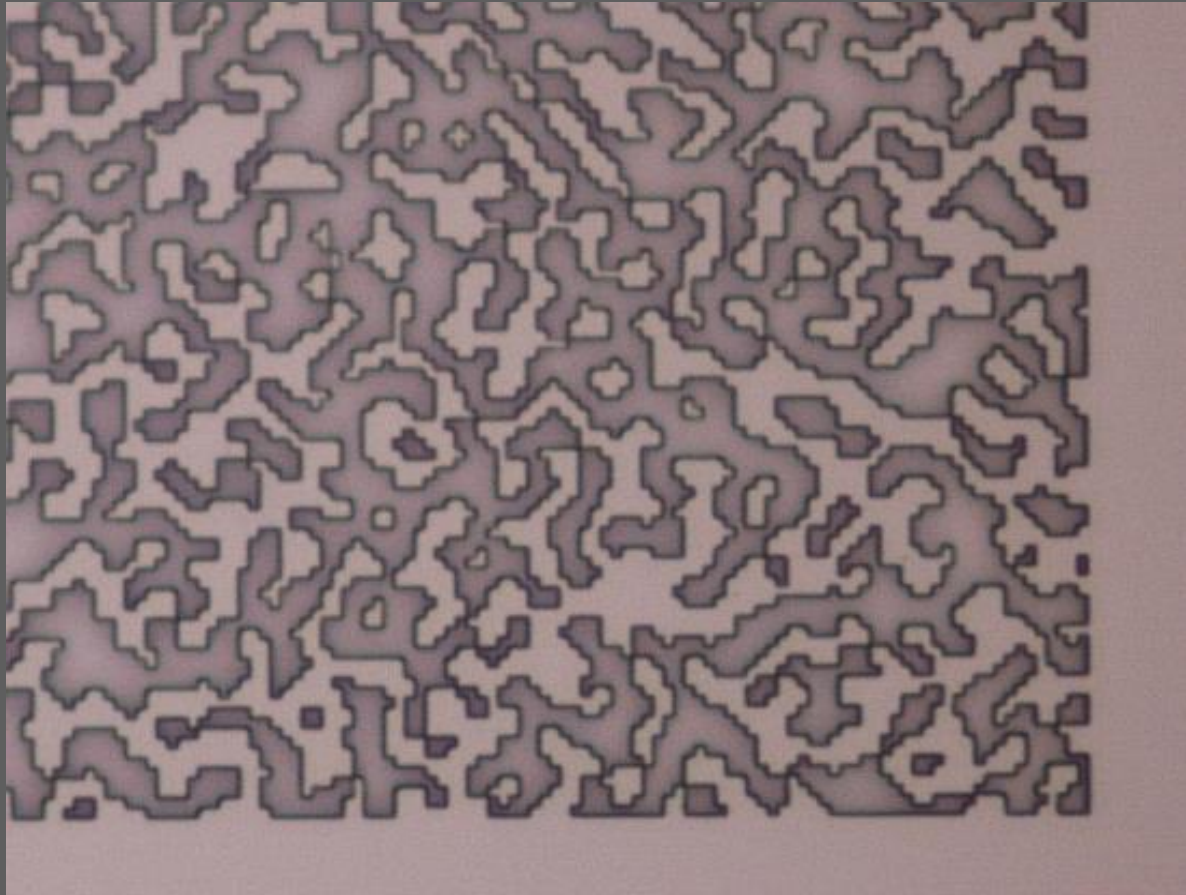
Advanced Lithography Materials for MOE



V. J. Einck, M. Torfeh, A. McClung, D. E. Jung, M. Mansouree, A. Arbabi, J. J. Watkins
ACS Photonics 2021, 8, 2400–2409

Organic etch mask materials for glass, semi etch

Advanced Lithography Materials for DOE

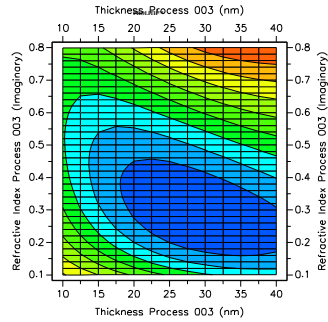


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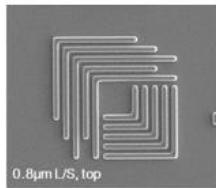
Si-based photoresist, metal oxide etch hard masks

PiBond's Litho Materials

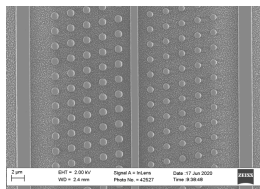
1. Stack and substrate modelling



2 & 3. High Si-% PR 'Bilayer resist' 'Patternable ML'

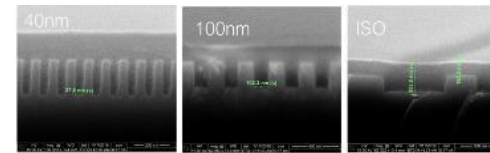
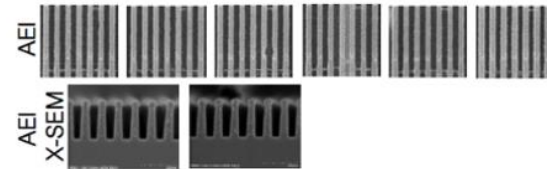
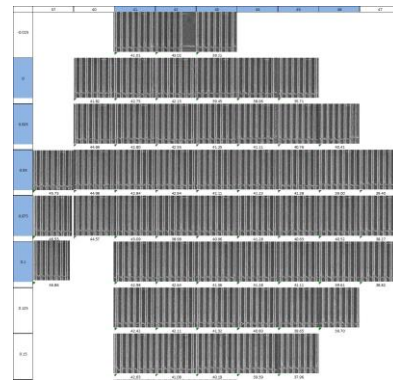


HP 22nm, CD(ave) 16nm
LER 1.0nm, LWR 1.4nm

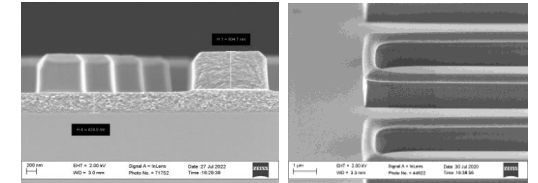


4. Extensive SiBARC, SiHM library

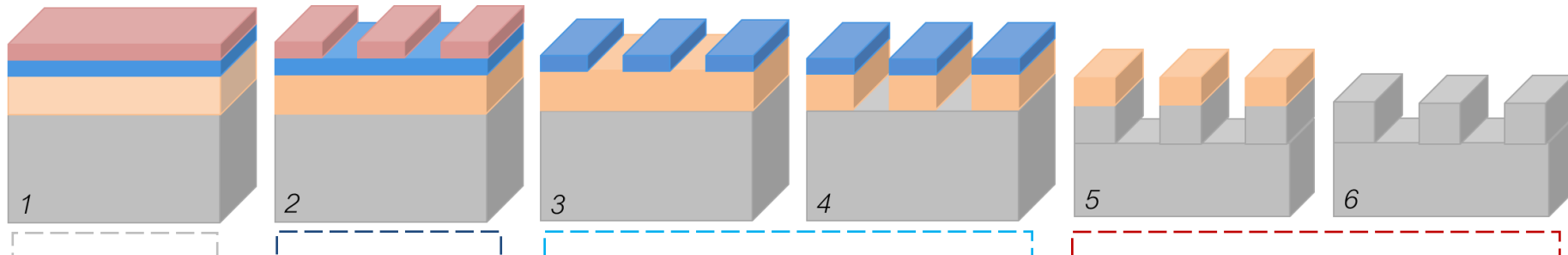
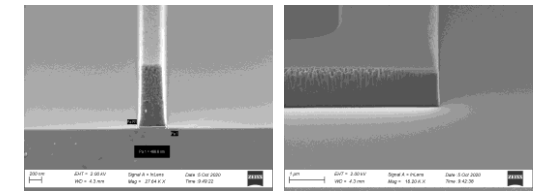
5. Spin-on carbon under layer Planarizing organic coatings



4 & 5. Etch process development

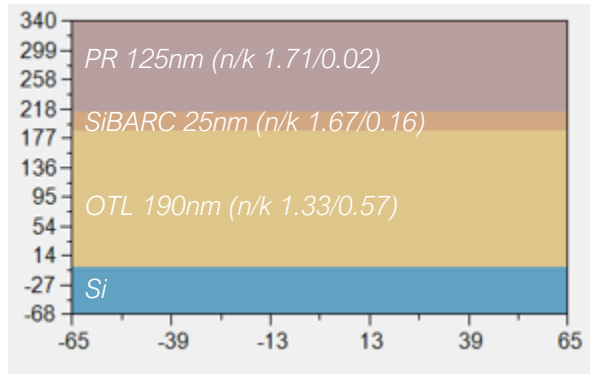


6. Strip solutions and removers

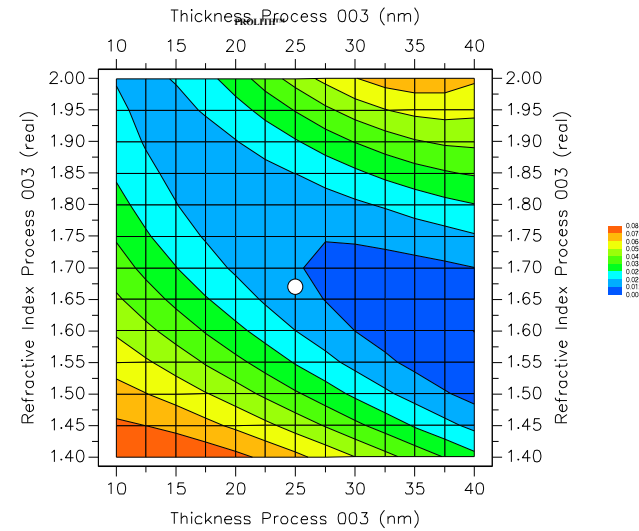


PiBond

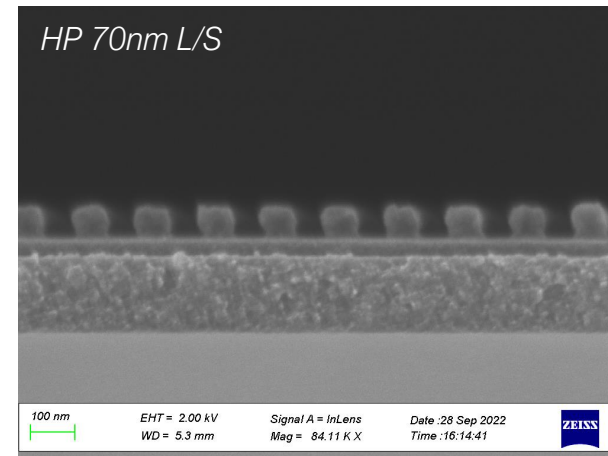
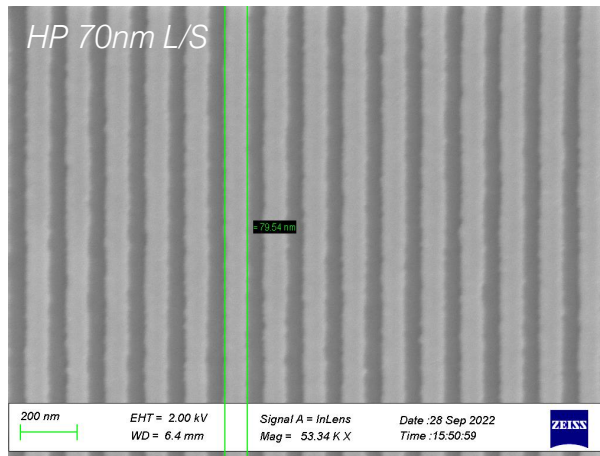
SiBARC & SOC – case study



Stack reflectivity 1.5%



- PiBond SiBARC and OTL thickness and nk adjusted to match photoresist and minimize stack reflectivity

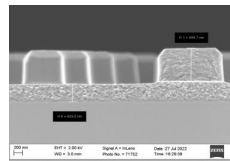
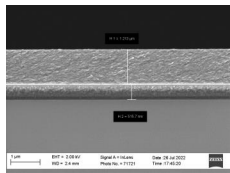
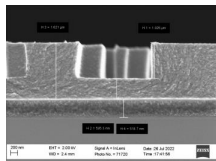


- ArF CAR patterned on PiBond SiBARC / OTL with 70nm L/S
- No peeling or pattern collapse

PiBond's Litho Materials

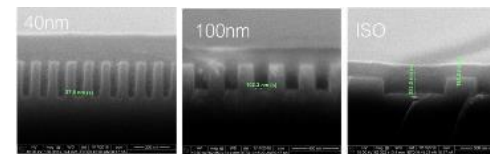
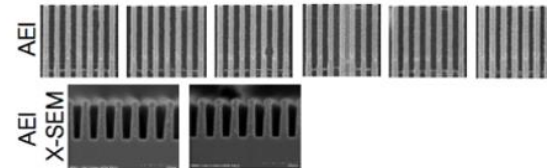
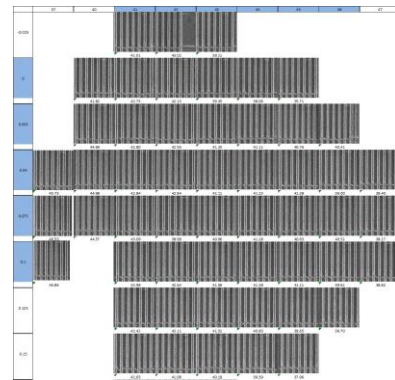
Nanoimprint Turnkey Solution

1. NIL Si-based resist

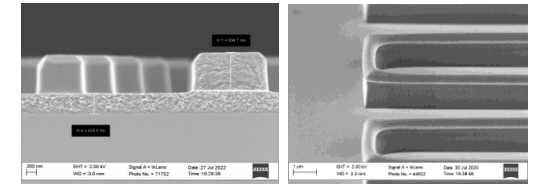


2. Extensive SiBARC, SiHM library

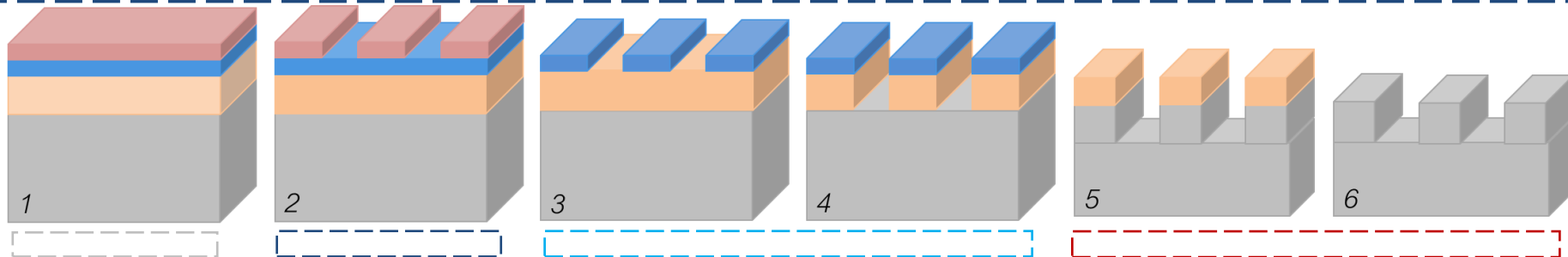
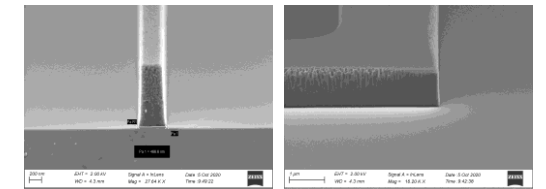
3. Spin-on carbon under layer Planarizing organic coatings



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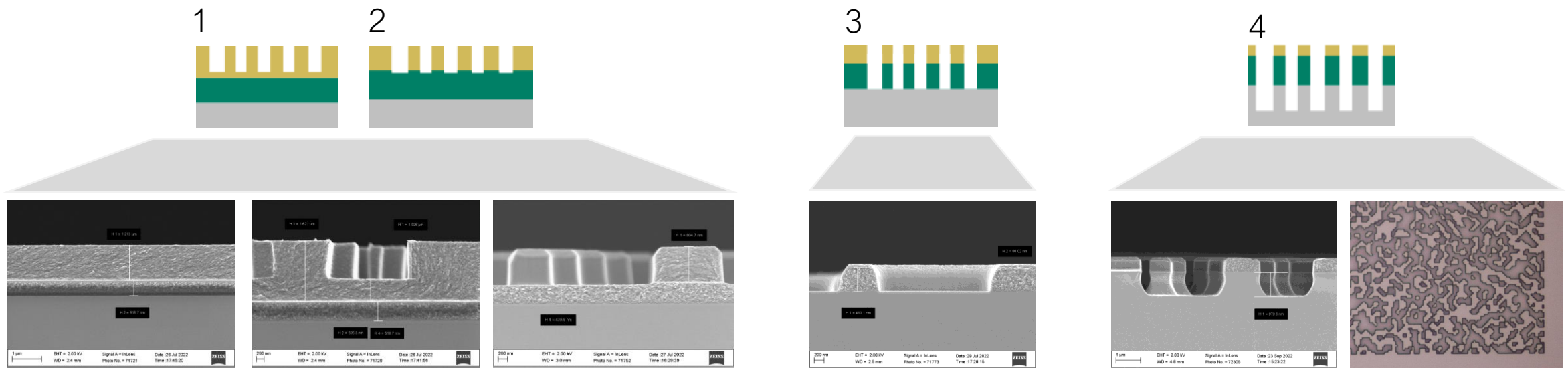


Silicon-based resist – case study

- **Need:** Complex patterns of 100-400nm dimensions. Variable size and pitch
- **Solution:** Use of PiBond's NIL Silicon-based resist and underlayer to transfer pattern to substrate.
- **Benefit:** Avoid costly and challenging optical lithography steps and metal hard masks (e.g. Cr, Ni)

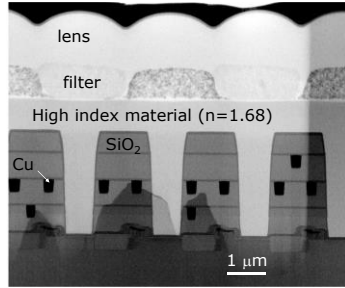
PROCESS FLOW

1. Coat underlayer and NIL Si-PR
2. Pattern NIL Si-PR
3. Pattern transfer to underlayer
4. Transfer to substrate and strip



PiBond materials in image sensors

Case example on optical coatings and materials for photonic applications



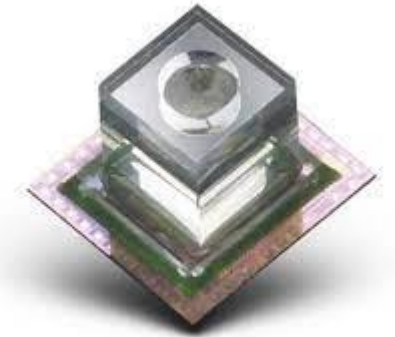
1. CMOS sensor die



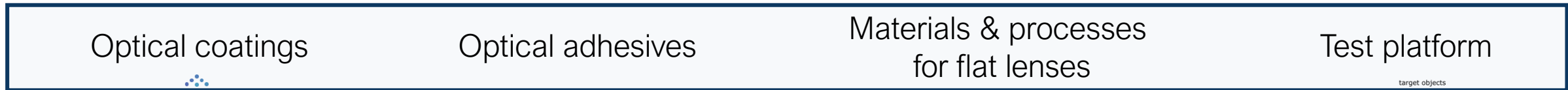
2. Wafer level packaging



3. Wafer level lenses and stacking

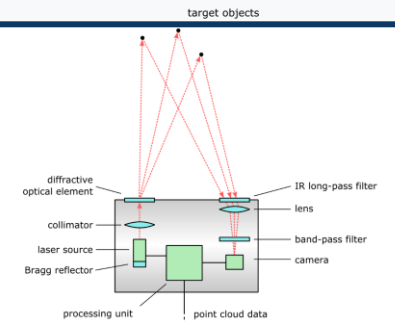
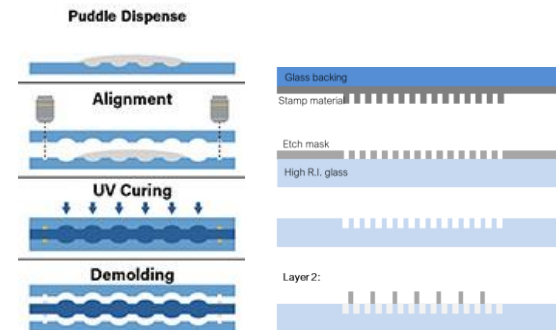


4. Singulation and integration



PiBond
SC optical coatings

- SC 300ip: High refractive index material with metal oxide nanoparticles
- SC 300i: High refractive index material for low <math><300^{\circ}\text{C}</math> temperature processes
- SC 400: High refractive index and high 400-450°C temperature stability
- SC 200: Planarizing gapfill material, High optical transparency also in UV
- SC 500: Low refractive index without fillers, Planarizing and conformal coatings, Up to 1μm coating thickness



PiBond

Materials

- Lithography materials
 - Advanced carbon and silicon rich etch mask materials
 - Silicon rich photoresists
 - Materials for both optical lithography and high index substrate patterning
- Optical coatings
 - High and low index coatings and adhesives

Concepts

- Wafer Level Optics including Meta Optical Elements

Thank You!